

**METHOD FOR SELECTING COMPONENTS FOR A
MATCHED SET FROM A WAFER-INTERPOSER ASSEMBLY**

ABSTRACT OF THE DISCLOSURE

A matched set of integrated circuit chips (24) and a method for assembling such integrated circuit chips (24) into a matched set are disclosed. A semiconductor wafer (18) having a plurality of integrated circuit chips (24) is electrically and mechanically coupled to a wafer interposer (12) to form a wafer-interposer assembly (10). The integrated circuit chips (24) of the wafer (18) are then tested together by attaching the wafer-interposer assembly (10) to a testing apparatus and running the integrated circuit chips (24) through various testing sequences. The wafer-interposer assembly (10) is then diced into a plurality of chip assemblies each having a chip (24) and a section of the wafer interposer (12). Based upon the testing, the chip assemblies are sorted and at least two of the chip assemblies are selected for inclusion in the matched set.

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